HEAT-DISSIPATING MODULE FOR REMOVING HEAT GENERATED FROM HEAT-GENERATING DEVICE

ABSTRACT OF THE DISCLOSURE

A heat-dissipating module includes a lower housing, a first magnet portion, a second magnet portion and a circuit board. The lower housing is made of a highly thermal conductive material. The upper housing has an opening in the center thereof, wherein when the upper housing and the lower housing are jointed together, an outlet is defined. The first magnet portion includes a plurality of first magnets. The second magnet portion has a plurality of second magnets, wherein a permanent magnetic field is formed between the plurality of first magnets and the plurality of second magnets. The circuit board is disposed between the first magnet portion and the second magnet portion and having a plurality of winding coils, wherein when a current is applied to the plurality of winding coils, the permanent magnetic field is repulsed to rotate the blade portion, and an ambient air flow is inhaled from the opening and exhaled via the outlet.